

S9S12GN48F1CLC :Part Detail

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General Information

Part Number	S9S12GN48F1CLC
Description	16-bit MCU, S12 core, 48KB Flash, 25MHz, -40/+85degC, Automotive Qualified, QFP 32
Product Line	G9FSG64C
PTI	JCGA
Material Type	Tested Packaged Device
Life Cycle Description (code)	PRODUCT STABLE GROWTH/MATURITY
Status	Active
Application/Qualification Tier	AUTO; >=10 YEARS APPLICATION LIFE

Package Information

Package Type and Termination Count	QFP 32
Package Description and Mechanical Drawing	LQFP 32 7*7*1.4P0.8
Device Weight(g)	0.18860
Package Material	Plastic
Mounting Style	Surface Mount
Package Length (nominal)(mm)	7.000
Package Width (nominal)(mm)	7.000
Package Thickness (nominal)(mm)	1.600
Maximum Height Above Board(mm)	1.600
Tape & Reel	No

Environmental and Compliance Information

Pb-Free	
RoHS Compliant	
Halogen Free	Yes
Material Composition Declaration (MCD)	Download MCD Report Download MCD Report
RoHS Certificate of Analysis (CoA)	Download RoHS CoA Report

Moisture Sensitivity Level (MSL)	3
Floor Life	168 HOURS
Peak Package Body Temperature (PPT)(°C)	260
Maximum Time at Peak Temperature (s)	40
Number of Reflow Cycles	3
REACH SVHC	NXP REACH Statement
UL94 (plastics flammability test)	V0;Burning stops within 10 seconds on a vertical specimen;no drips allowed

Manufacturing Information

Micron Size(μm)	.18
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Ordering Information

Minimum Package Quantity (MPQ)	250
MPQ Container	TRAY
Exempt from Minimum Delivery Value	No
Preferred Order Quantity (POQ)	1250
POQ Container	BOX
Export Control Classification Number (US)	3A991A2
Harmonized Tariff (	
CCATS Document	-
ENC Status	-
Other Trade Compliance Documents	-
Budgetary Price excluding tax(US Currency)	1 @ US each
Order	

Operating Characteristics

Sample Exception Availability	N
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